December 5, 2017

Microsoft Azure Becomes First Global Cloud Provider to Deploy AMD EPYC™

— Microsoft's Project Olympus Hardware Design Powered by the AMD EPYC Processor Now Deployed in Azure —

— New L-Series Storage Instance Leverages Massive PCIe™ Connectivity and High Performance of AMD EPYC Processors —

SUNNYVALE, Calif., Dec. 05, 2017 (GLOBE NEWSWIRE) -- AMD (NASDAQ:AMD) today announced the first public cloud instances powered by the AMD EPYC™ processor. Microsoft Azure has deployed AMD EPYC processors in its datacenters in advance of preview for its latest L-Series of Virtual Machines (VM) for storage optimized workloads. The Lv2 VM family will take advantage of the high-core count and connectivity support of the AMD EPYC processor.

"We are extremely excited to be partnering with Microsoft Azure to bring the power of AMD EPYC processors into their datacenter," said Scott Aylor, corporate vice president and general manager of Enterprise Solutions. "There is tremendous opportunity for users to tap into the capabilities we can deliver across storage and other workloads through the combination of AMD EPYC processors on Azure. We look forward to the continued close collaboration with Microsoft Azure on future instances throughout 2018."

Corey Sanders, director of compute, Microsoft Azure, Microsoft Corp, said, "We're welcoming AMD's new EPYC processor to Microsoft Azure with the next generation of our L-Series Virtual Machines. The new Lv2-Series are High I/O, dense storage offerings which make EPYC perfect for Azure customers' demanding workloads. We've enjoyed a deep collaboration with AMD on our next generation open source cloud hardware design called Microsoft's Project Olympus. We think Project Olympus will be the basis for future innovation between Microsoft and AMD, and we look forward to adding more instance types in the future benefiting from the core density, memory bandwidth and I/O capabilities of AMD EPYC processors."

The Lv2-Series instances run on the AMD EPYC 7551 processor, featuring a base core frequency of 2.2 GHz and a maximum single-core turbo frequency of 3.0 GHz. With support for 128 lanes of PCIe connections per processor, AMD provides over 33 percent more connectivity than available two-socket solutions[1] to address an unprecedented number of NVMe drives directly.

The Lv2 VMs will be available starting at eight and ranging to 64 vCPU sizes, with the largest size featuring direct access to 4TB of memory. These sizes will support Azure premium storage disks by default and will also support accelerated networking capabilities for the highest throughput of any cloud. With the unique capabilities enabled by AMD EPYC processors and Microsoft Azure, Lv2 is a perfect fit for storage-intensive workloads.

The Lv2-Series instances are based on Microsoft's Project Olympus design, first introduced just over a year ago as Microsoft's next generation hyperscale cloud hardware design. This groundbreaking design serves as a new model for open source hardware development with the Open Compute Project community.

Additional Resources

- Microsoft Azure Blog on AMD EPYC
- AMD EPYC on AMD.com
- Follow AMD datacenter developments on Twitter @AMDServer

About AMD
For more than 45 years, AMD has driven innovation in high-performance computing, graphics and visualization technologies — the building blocks for gaming, immersive platforms, and the datacenter. Hundreds of millions of consumers, leading Fortune 500 businesses and cutting-edge scientific research facilities around the world rely on AMD technology daily to improve how they live, work and play. AMD employees around the world are focused on building great products that push the boundaries of what is possible. For more information about how AMD is enabling today and inspiring tomorrow, visit the AMD (NASDAQ:AMD) website, blog, and Facebook and Twitter pages.

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[1]The AMD EPYC processor supports up to 128 lanes of PCIe Gen 3 (both 1 socket and 2 socket configurations) on every product. The Intel Scalable Processor supports a maximum of 48 lanes of PCIe Gen 3 per CPU and 20 lanes in the I/O chip. (max of 68 lanes on 1 socket and 96 lanes on 2 socket) on all CPU's.

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Cautionary Statement

This press release contains forward-looking statements concerning Advanced Micro Devices, Inc. (AMD) including the collaboration with Microsoft Azure throughout 2018, Project Olympus, the features, functionality, availability, and timing on products, and expected benefits of the collaboration between AMD and Microsoft Azure, which are made pursuant to the Safe Harbor provisions of the Private Securities Litigation Reform Act of 1995. Forward-looking statements are commonly identified by words such as "would," "intends," "believes," "expects," "may," "will," "should," "seeks," "intends," "plans," "pro forma," "estimates," "anticipates," or the negative of these words and phrases, other variations of these words and phrases or comparable terminology. Investors are cautioned that the forward-looking statements in this document are based on current beliefs, assumptions and expectations, speak only as of the date of this document and involve risks and uncertainties that could cause actual results to differ materially from current expectations. Such statements are subject to certain known and unknown risks and uncertainties, many of which are difficult to predict and generally beyond AMD's control, that could cause actual results and other future events to differ materially from those expressed in, or implied or projected by, the forward-looking information and statements. Material factors that could cause actual results to differ materially from current expectations include, without limitation, the following: Intel Corporation's dominance of the microprocessor market

and its aggressive business practices may limit AMD's ability to compete effectively; AMD has a wafer supply agreement with GF with obligations to purchase all of its microprocessor and APU product requirements, and a certain portion of its GPU product requirements, from GLOBALFOUNDRIES Inc. (GF) with limited exceptions. If GF is not able to satisfy AMD's manufacturing requirements, its business could be adversely impacted; AMD relies on third parties to manufacture its products, and if they are unable to do so on a timely basis in sufficient quantities and using competitive technologies, AMD's business could be materially adversely affected; failure to achieve expected manufacturing yields for AMD's products could negatively impact its financial results; the success of AMD's business is dependent upon its ability to introduce products on a timely basis with features and performance levels that provide value to its customers while supporting and coinciding with significant industry transitions; if AMD cannot generate sufficient revenue and operating cash flow or obtain external financing, it may face a cash shortfall and be unable to make all of its planned investments in research and development or other strategic investments; the loss of a significant customer may have a material adverse effect on AMD; AMD's receipt of revenue from its semi-custom SoC products is dependent upon its technology being designed into third-party products and the success of those products; global economic uncertainty may adversely impact AMD's business and operating results; the markets in which AMD's products are sold are highly competitive; AMD may not be able to generate sufficient cash to service its debt obligations or meet its working capital requirements; AMD has a large amount of indebtedness which could adversely affect its financial position and prevent it from implementing its strategy or fulfilling its contractual obligations; the agreements governing AMD's notes and the Secured Revolving Line of Credit impose restrictions on AMD that may adversely affect its ability to operate its business; AMD's issuance to West Coast Hitech L.P. (WCH) of warrants to purchase 75 million shares of its common stock, if and when exercised, will dilute the ownership interests of its existing stockholders, and the conversion of the 2.125% Convertible Senior Notes due 2026 may dilute the ownership interest of its existing stockholders, or may otherwise depress the price of its common stock; uncertainties involving the ordering and shipment of AMD's products could materially adversely affect it; the demand for AMD's products depends in part on the market conditions in the industries into which they are sold. Fluctuations in demand for AMD's products or a market decline in any of these industries could have a material adverse effect on its results of operations; AMD's ability to design and introduce new products in a timely manner is dependent upon third-party intellectual property; AMD depends on third-party companies for the design, manufacture and supply of motherboards, software and other computer platform components to support its business; if AMD loses Microsoft Corporation's support for its products or other software vendors do not design and develop software to run on AMD's products, its ability to sell its products could be materially adversely affected; and AMD's reliance on third-party distributors and AIB partners subjects it to certain risks. Investors are urged to review in detail the risks and uncertainties in AMD's Securities and Exchange Commission filings, including but not limited to AMD's Quarterly Report on Form 10-Q for the quarter ended September 30, 2017.

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Source: Advanced Micro Devices